

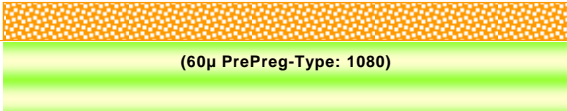

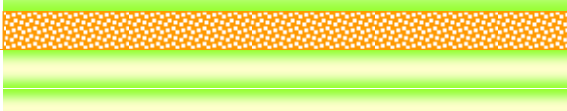







**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**10 175 FR4 35 L20.35 P06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**10\_175\_FR4\_35\_L20.35\_p06**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	35 $\mu$	Copper		A1
	60 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		A2
	200 $\mu$	L-FR4		
<b>Layer-3</b>	35 $\mu$	Copper		A3
	60 $\mu$	Prepreg		
<b>Layer-4</b>	35 $\mu$	Copper		A4
	60 $\mu$	Prepreg		
<b>Layer-5</b>	35 $\mu$	Copper		A1
	200 $\mu$	L-FR4		
<b>Layer-6</b>	35 $\mu$	Copper		A2
	60 $\mu$	Prepreg		
<b>Layer-7</b>	35 $\mu$	Copper		A3
	60 $\mu$	Prepreg		
<b>Layer-8</b>	35 $\mu$	Copper		A4
	200 $\mu$	L-FR4		
<b>Layer-9</b>	35 $\mu$	Copper		A1
	60 $\mu$	Prepreg		
<b>Layer-99</b>	35 $\mu$	Copper		A2
	60 $\mu$	Prepreg		

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